

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
 Stylesheet Version v1.2

EPAS ID: PAT3542448

|   |  |                       |
|---|--|-----------------------|
| <b>SUBMISSION TYPE:</b>   | NEW ASSIGNMENT   |                       |
| <b>NATURE OF CONVEYANCE:</b>  | ASSIGNMENT   |                       |
| <b>CONVEYING PARTY DATA</b>   |  |                       |
|   | <b>Name</b>  | <b>Execution Date</b> |
|   | SEUNG TAEK YANG  | 08/03/2015            |
| <b>RECEIVING PARTY DATA</b>   |  |                       |
| <b>Name:</b>  | SK HYNIX INC.  |                       |
| <b>Street Address:</b>  | 2091, GYEONGCHUNG-DAERO, BUBAL-EUB                         |                       |
| <b>City:</b>  | ICHEON-SI GYEONGGI-DO                                      |                       |
| <b>State/Country:</b>   | KOREA, REPUBLIC OF   |                       |
| <b>PROPERTY NUMBERS Total: 1</b>  |  |                       |
|   | <b>Property Type</b>                                       | <b>Number</b>         |
|   | <b>Application Number:</b>                                 | 14865189              |
| <b>CORRESPONDENCE DATA</b>  |  |                       |
| <b>Fax Number:</b>  | (630)323-0335  |                       |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> |  |                       |
| <b>Phone:</b>   | 6309087652   |                       |
| <b>Email:</b>   | uspto.actions@wpapat.com                                   |                       |
| <b>Correspondent Name:</b>  | WILLIAM PARK & ASSOCIATES LTD.                             |                       |
| <b>Address Line 1:</b>  | 930 N. YORK ROAD, SUITE 201                                |                       |
| <b>Address Line 4:</b>  | HINSDALE, ILLINOIS 60521                                   |                       |
| <b>ATTORNEY DOCKET NUMBER:</b>  | PA1143-1D  |                       |
| <b>NAME OF SUBMITTER:</b>   | WOOCHOON W. PARK   |                       |
| <b>SIGNATURE:</b>   | /Woochoon W. Park/   |                       |
| <b>DATE SIGNED:</b>   | 09/25/2015   |                       |
|   | This document serves as an Oath/Declaration (37 CFR 1.63). |                       |
| <b>Total Attachments: 1</b>   |  |                       |
| source=PA1143-1D_Declaration_Assignment#page1.tif   |  |                       |

**DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION  
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

|                                   |   |                        |
|-----------------------------------|---|------------------------|
| <b>Title of<br/>Invention</b>     | SUBSTRATE INCLUDING A DAM FOR SEMICONDUCTOR PACKAGE,<br>SEMICONDUCTOR PACKAGE USING THE SAME, AND MANUFACTURING METHOD<br>THEREOF   |                        |
| <b>Declaration</b>                | <p>As the below named inventor(s), I hereby declare that:<br/> The declaration is directed to:<br/> <input checked="" type="checkbox"/> The attached application, or<br/> <input type="checkbox"/> United States application or PCT international application number<br/> <u>PCT/KR#####</u> filed on _____</p> <p>The above-identified application was made or authorized to be made by me.<br/> I believe that I am the original or an original joint inventor of a claimed invention in the<br/> application.<br/> I hereby acknowledge that any willful false statement made in this declaration is punishable<br/> under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years or both.</p>   |                        |
| <b>Assignment</b>                 | <p>NOW, THEREFORE, in consideration of the sum of one dollar (\$1), the receipt whereof is<br/> acknowledge, and other good and valuable consideration, I, by these presents do sell, assign<br/> and transfer unto said assignee(s)</p> <p align="center"><b>SK hynix Inc.</b><br/> <b>2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-do, Korea</b></p> <p>and the heirs, successors, assigns and legal representatives of the assignee(s) the full and<br/> exclusive right to the said invention in the United States and in its territorial possessions and<br/> in any and all foreign countries any and all improvements thereof, the entire rights, title and<br/> interest in and to any and all Patents which may be granted therefore in the United States. I<br/> hereby authorize and request the Director of the U.S. Patent and Trademark Office to issue<br/> said United States Patent to said assignee(s), of the entire right, title, and interest in and to<br/> the same, for his sole use and for the use of his legal representatives, to the full end of the<br/> term for which said Patent may be granted, as fully and entirely as the same would have<br/> been held by me had this assignment and sale not been made.</p> <p>I agree promptly upon request of the assignee(s), its heirs, successors, assigns and legal<br/> representatives of the assignee(s) to communicate any facts known to it respecting the<br/> patent and the invention set forth therein, and to execute and deliver without further<br/> compensation any power of attorney, Assignment, application, whether original, continuation,<br/> divisional or reissue, or other papers that may be necessary.</p> <p>I hereby covenant that no assignment, sale agreement or encumbrance has been or will be<br/> made or entered into which would conflict with this assignment and sale.</p> <p>I further covenant that assignee(s) will, upon its request, be provided promptly with all<br/> pertinent facts and documents relating to said invention and said Letters Patent and legal<br/> equivalents as may be known and accessible to me and will testify as to the same in any<br/> litigation related thereto and will promptly execute and deliver to assignee(s) or its legal<br/> representatives any and all papers, instruments or affidavits required to apply for, obtain,<br/> maintain, issue and enforce said application, said invention and said Letters Patent and said<br/> equivalents thereof which may be necessary or desirable to carry out the purposes thereof.</p> |                        |
| <b>Legal Name<br/>Of Inventor</b> | Inventor Name (First Middle LAST):  | Seung Taek YANG        |
|                                   | Inventor Signature:   | <i>Seung Taek YANG</i> |
|                                   | Date:   | 15' / 03 / <i>Aug</i>  |

**PATENT**

**REEL: 036654 FRAME: 0588**